**AGREEMENT FOR TRANSFER OF COPYRIGHT**

Copyright to the following article: Title:

Author:

I hereby transferred to the JSPS 191st Committee on Innovative Interface Bonding Technology, effective when the article is accepted by the Committee for publication of 2019 6th International Workshop on Low Temperature Bonding for 3D Integration (LTB-3D) in any of its publications.

(This form is to be signed by at least one of the authors, who agree to inform the other authors, if any, or if this article has been prepared as a "work for hire" by the author for his employer, this form is to be signed by the employer.)

Signature

Printed Name

Title, if signed by the employer of the author

Date

**LTB-3D 2019**